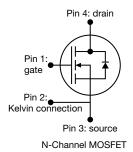


Vishay Siliconix

## **E Series Power MOSFET**

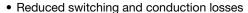




PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700	)			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.316			
Q <sub>g</sub> max. (nC)	68				
Q <sub>gs</sub> (nC)	9				
Q <sub>gd</sub> (nC)	15				
Configuration	Single				

#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)



- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise

 Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>





GREEN

(5-2008)

### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH11N65E-T1-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			$V_{DS}$	650	V
Gate-Source Voltage			$V_{GS}$	± 30	v
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C	- I <sub>D</sub>	12	
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		8	Α
Pulsed Drain Current a			I <sub>DM</sub>	27	
Linear Derating Factor				1	W/°C
Single Pulse Avalanche Energy b			E <sub>AS</sub>	127	mJ
Maximum Power Dissipation			P <sub>D</sub>	130	W
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-Source Voltage Slope T <sub>J</sub> = 125 °C			4).//d+	70	1//20
Reverse Diode dV/dt <sup>c</sup>			dV/dt	24	V/ns

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 3 A.
- c.  $I_{SD} \leq I_D$ , dI/dt = 100 A/ $\mu s$ , starting  $T_J = 25$  °C.



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	42	55	°C/W	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	0.72	0.96	G/VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	650	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.77	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
0.1. 0		1	$V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Gate-Source Leakage	I <sub>GSS</sub>	\	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA
Zana Oata Valta na Duain Oannant		V <sub>DS</sub> =	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V		-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 520 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	50	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 6 A	-	0.316	0.363	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 6 A		-	4.1	-	S
Dynamic							•
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	1257	-	
Output Capacitance	C <sub>oss</sub>	,	$V_{\rm DS} = 100 \text{ V},$	-	60	-	
Reverse Transfer Capacitance	$C_{rss}$		f = 1 MHz	-	4	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>		/+- 500 V V 0 V	-	43	-	pF
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>	V <sub>DS</sub> = 0 V	/ to 520 V, V <sub>GS</sub> = 0 V	-	168	-	
Total Gate Charge	Qg			-	34	68	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 6 A, V_{DS} = 520 V$	-	9	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			-	15	-	
Turn-On Delay Time	t <sub>d(on)</sub>			-	19	38	
Rise Time	t <sub>r</sub>	V <sub>DD</sub> =	= 520 V, I <sub>D</sub> = 6 A,	-	28	56	
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$= 10 \text{ V}, \text{ R}_{\text{g}} = 9.1 \Omega$	-	39	78	ns
Fall Time	t <sub>f</sub>			-	23	46	
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET sym showing the	bol	-	-	12	^
Pulsed Diode Forward Current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	27	- A
Diode Forward Voltage	$V_{SD}$	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 6 A, V <sub>GS</sub> = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			-	321	642	ns
Reverse Recovery Charge	Q <sub>rr</sub>		5 °C, I <sub>F</sub> = I <sub>S</sub> = 6 A, 100 A/µs, V <sub>B</sub> = 25 V	-	3.8	7.6	μC
Reverse Recovery Current	I <sub>RRM</sub>		100 AV 40, VR = 20 V	-	19	-	Α

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

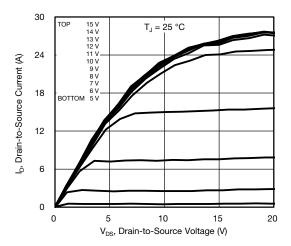


Fig. 1 - Typical Output Characteristics

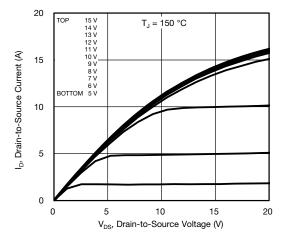


Fig. 2 - Typical Output Characteristics

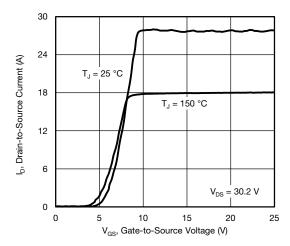


Fig. 3 - Typical Transfer Characteristics

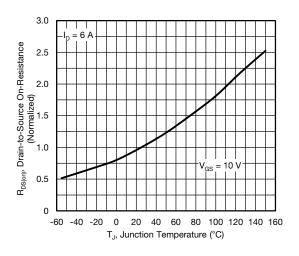


Fig. 4 - Normalized On-Resistance vs. Temperature

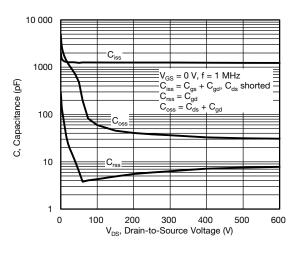


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

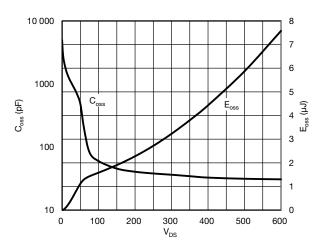


Fig. 6 -  $C_{OSS}$  and  $E_{OSS}$  vs.  $V_{DS}$ 



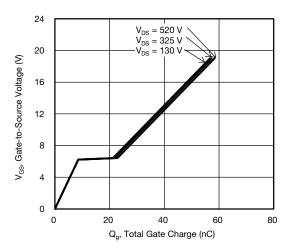


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

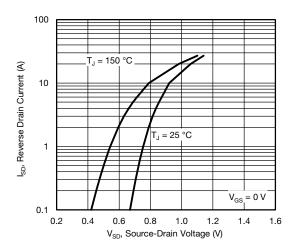


Fig. 8 - Typical Source-Drain Diode Forward Voltage

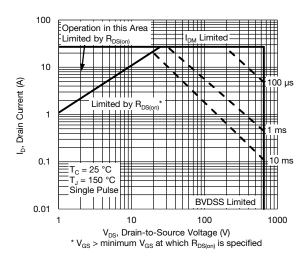


Fig. 9 - Maximum Safe Operating Area

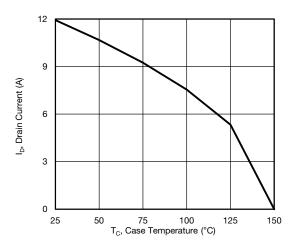


Fig. 10 - Maximum Drain Current vs. Case Temperature

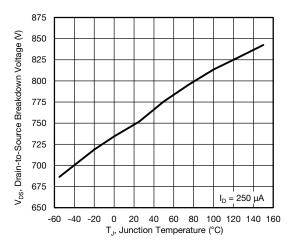


Fig. 11 - Temperature vs. Drain-to-Source Voltage



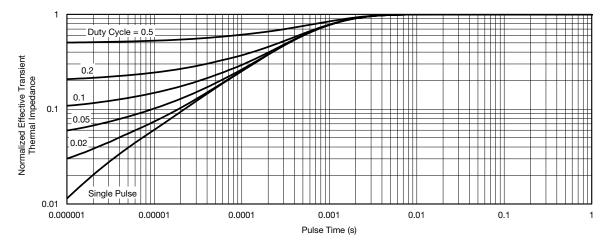


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

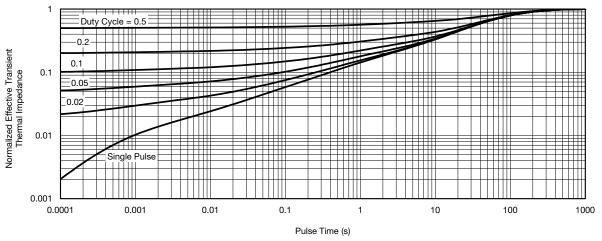


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

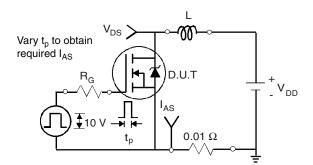


Fig. 14 - Switching Time Test Circuit

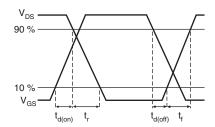


Fig. 15 - Switching Time Waveforms



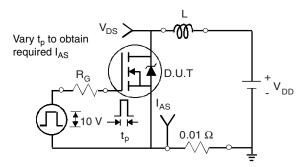


Fig. 16 - Unclamped Inductive Test Circuit

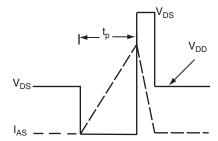


Fig. 17 - Unclamped Inductive Waveforms

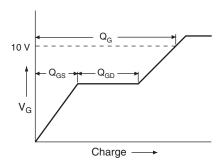


Fig. 18 - Basic Gate Charge Waveform

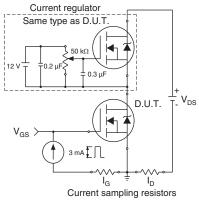
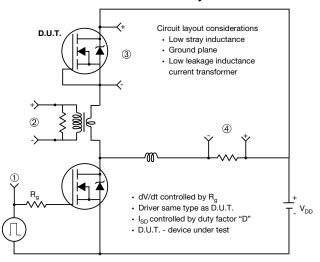


Fig. 19 - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



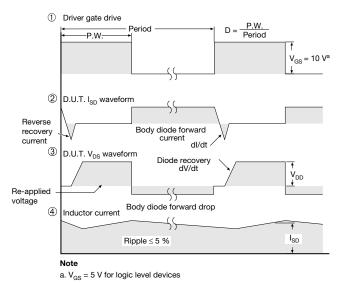


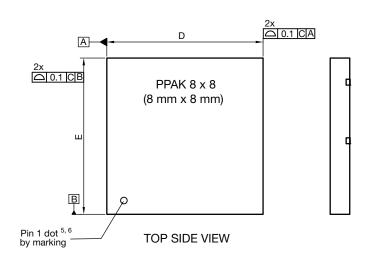
Fig. 20 - For N-Channel

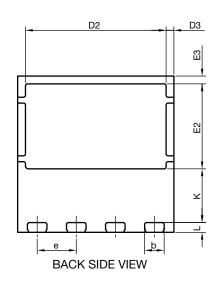
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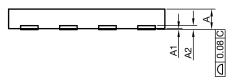


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# PowerPAK® 8 x 8 Case Outline







DIM.	MILLIMETERS			INCHES			
DIIVI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2	020 ref.			0.008 ref.			
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3	0.40 BSC			0.016 BSC			
е	2.00 BSC		0.079 BSC				
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC			0.016 BSC			
K	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N <sup>(3)</sup>	8			8 8			

#### Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

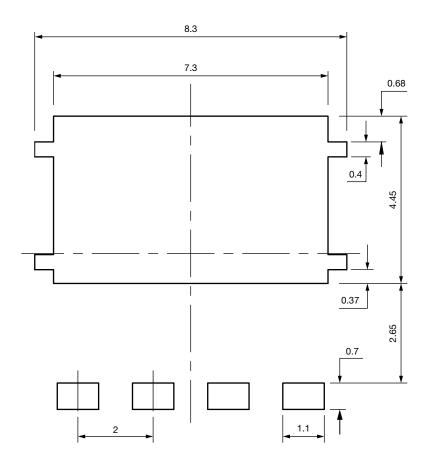
ECN: E20-0518-Rev. B, 28-Sep-2020

DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



# Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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